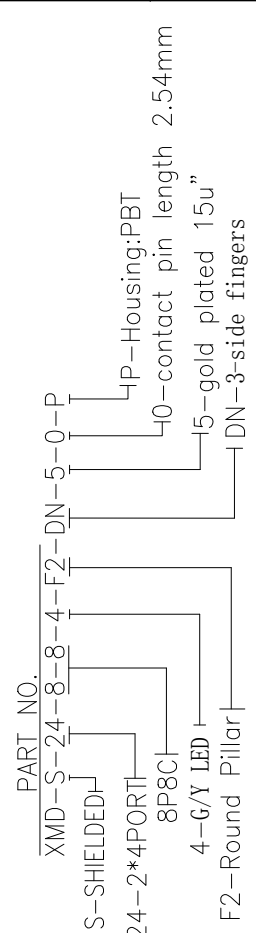
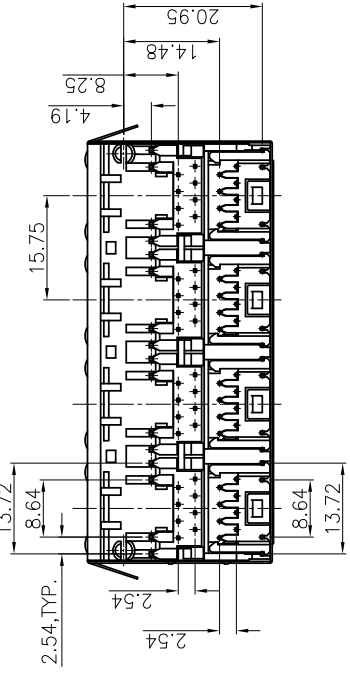
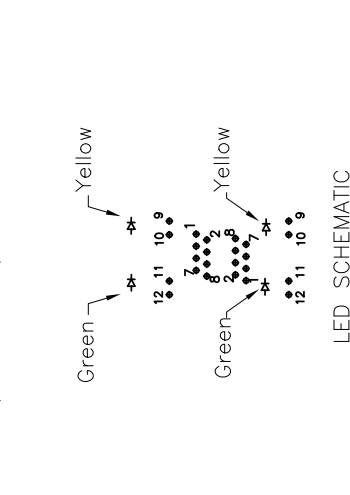
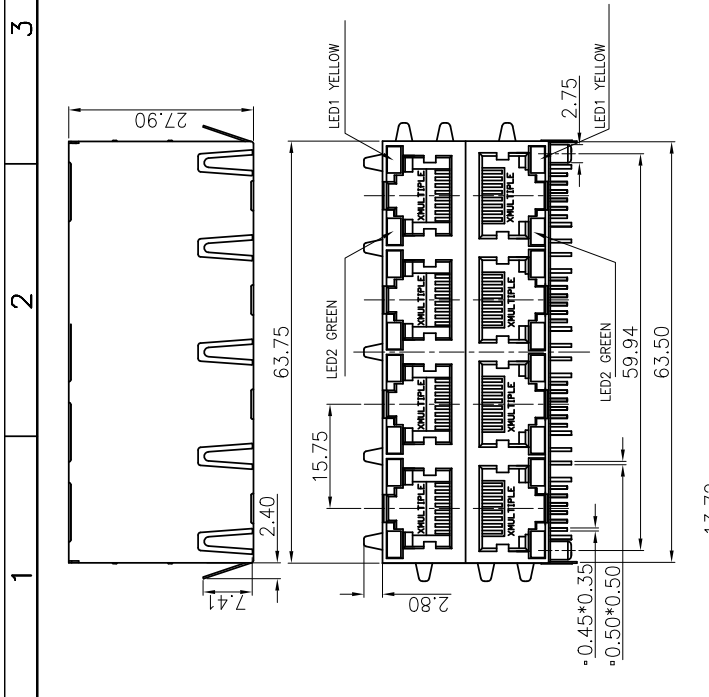
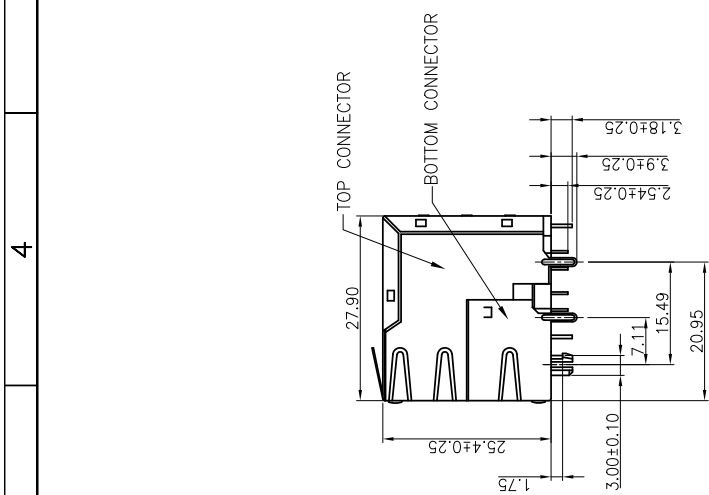


REV.	ECN.NO.	NAME	DATE
A	NEW	KEN	2010/05/11



NOTES:

- 1.MATERIAL:  
HOUSING:HIGH TEMP.THERMOPLASTIC,BLACK,PBT UL 94V-0  
CONTACT:PHOSPHOR BORNEZE,T=0.35MM.  
SHELL:BRASS,T=0.25MM.
- 2.FINISH:  
CONTACT:50u"MIN. NICKEL UNDERPLATING ALL AREA,  
100u"MIN. TIN ON SOLDERTAILS,  
15u"MIN. GOLD PLATING ON CONTACT AREA.  
SHELL:30u"MIN. NICKEL UNDERPLATING ALL AREA  
SHELL: T=0.25mm COPPER ZINC ALLOY PLATED WITH NICKEL  
3.OPERATING TEMPERATURE:-40°C~+85°C.
- 4.JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F



TOLERANCE UNSPECIFIED .0 ±0.5 .00 ±0.38 .000 ±0.25 ±0.10 ±.3° ANGLE MANUFACTURING COPY	X MULTIPLE		CONNECTING THE INFORMATION AGE
	TITLE: RJ45 Connectors, w/LED, 8P, 8C, Shielded/Thru Hole		
DRAWN BY: STEVEN	SIZE: A4	UNIT: mm	PART NO: XMD-S-24-8-8-4-F2-DN-5-0-P
CHECKED BY:	SCALE: 1:1		PROJECTION
APPROVED BY:	DWG . PATH		REV: A
			SHEET: 1 OF 1

SUGGESTED PCB LAYOUT